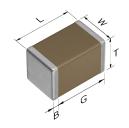
## 积层贴片陶瓷片式电容器

C2012X6S1H225K085AC RoHS Reach Halogen Free Pb Free

交货型号	C2012X6S1H225KT****	
用途	一般等级	
特点	General 一般(~75V)	
系列	C2012 [EIA 0805]	
状态	金 量产体制(新设计非推荐) 推荐代替型号: <u>C2012X7R1H225K125AC</u> (不保证其兼容性。)	



尺寸		
长度(L)	$2.00 \text{mm} \pm 0.20 \text{mm}$	
宽度(W)	1. 25mm $\pm 0.20$ mm	
厚度(T)	$0.85 \text{mm} \pm 0.15 \text{mm}$	
端子宽度(B)	0.20mm Min.	
端子间隔(G)	0.50mm Min.	
₩ 共相 Å 左 巳 / DA \	1.00mm to 1.30mm(Flow Soldering)	
推荐焊盘布局(PA)	0.90mm to 1.20mm(Reflow Soldering)	
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)	
进行杆益仰向(LD)	0.70mm to 0.90mm (Reflow Soldering)	
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)	
1世44/开洫41/内(I U)	0.90mm to 1.20mm(Reflow Soldering)	

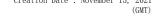
ŧ	<b>点特性</b>
电容	$2.2\muF\pm 10\%$
额定电压	50VDC
温度特性	X6S (±22%)
耗散因数(Max.)	5%
绝缘电阻 (Min.)	227ΜΩ

	其他	
焊接方法	流体	
件按月伝	回流	
AEC-Q200	NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.



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特性图表(这是参考数据,并不保证产品的特性。)

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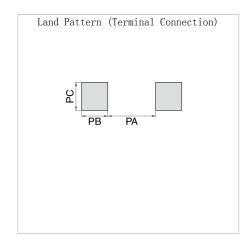
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## Associated Images



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